

# Supporting information

## Electrically conducting polymers as templating binding interfaces for fabrication of copper nanotubes

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By electroless deposition of copper on fiber template for longer time, we were able to control the extraneous deposition of the copper particles in between fiber template. This work is ongoing as we fabricate metal tubes with varied wall thickness and study their properties as a function of wall thickness. Here we present a sample TEM image of copper tube fabricated by plating for 40 minutes. Increased plating time gives tubes with thick wall thickness and a more uniform surface. However, it's hard to report the tubular structure of a tube by using TEM due to wall thickness. This information is contained in unpublished manuscript of an ongoing research project.

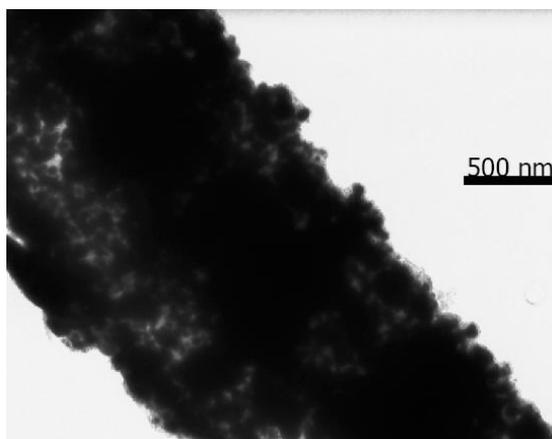


Fig. 1: TEM image of copper tube with a thick wall thickness.